SSC8323GN2

Dual P-Channel Enhancement Mode MOSFET

➢ Features

VDS	VGS	RDSON Typ.	ID
-20V	±12V	63mR@-4V5	-4A
		87mR@-2V5	
		120mR@-1V8	

➢ Description

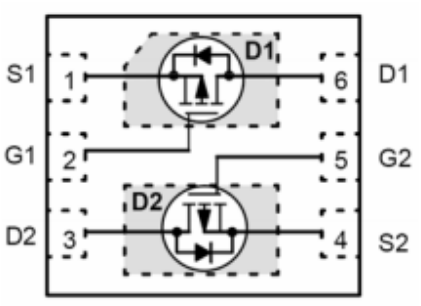
SSC8323GN2 combines 2 P-Channel enhancement mode power MOSFETs which are produced with high cell density and DMOS trench technology. This device particularly suits low voltage applications, especially for battery powered circuits, the tiny and thin outline saves PCB consumption.

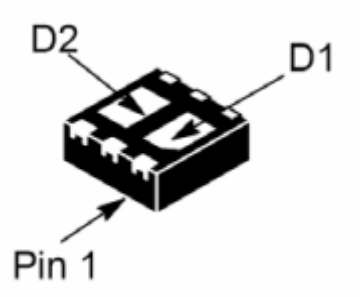
➢ Applications

- Li Battery Charging
- High Side DC/DC Converter
- Load Switch
- Powered Devices
- Power Management in Portable, Battery

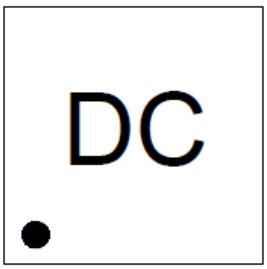
➢ Pin configuration

Top view





Bottom View



Marking

➢ Ordering Information

Device	Package	Shipping
SSC8323GN2	DFN2x2	3000/Reel

➢ Absolute Maximum Ratings(T_A=25℃ unless otherwise noted)

Symbol	Parameter	Ratings	Unit
V_{DSS}	Drain-to-Source Voltage	-20	V
V_{GSS}	Gate-to-Source Voltage	±12	V
I_D	Continuous Drain Current [a]	-4	A
I_{DM}	Pulsed Drain Current [b]	-20	A
P_D	Power Dissipation [c]	1.8	W
P_{DSM}	Power Dissipation [a]	0.9	W
T_J	Operation junction temperature	-55 to 150	℃
T_{STG}	Storage temperature range	-55 to 150	℃

➢ Thermal Resistance Ratings(T_A=25℃ unless otherwise noted)

Symbol	Parameter	Typical	Maximum	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance [a]		145	℃/W
$R_{\theta JC}$	Junction-to-Case Thermal Resistance		75	

Note:

a. The value of RθJA is measured with the device mounted on 1 in^2 FR-4 board with 2oz.copper,in a still air environment with TA=25℃.The value in any given application depends on the user is specific board design. The current rating is based on the t≤ 10s thermal resistance rating.

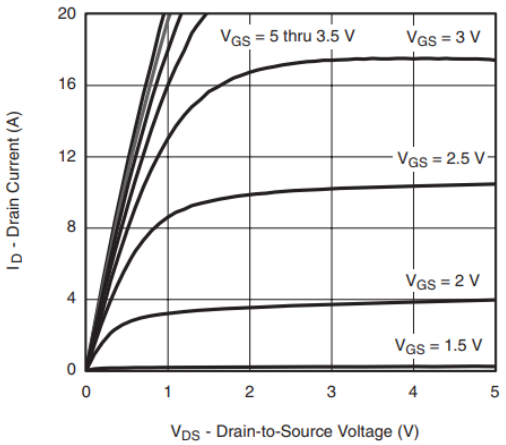
b. Repetitive rating, pulse width limited by junction temperature.

c. The power dissipation PD is based on TJ(MAX)=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

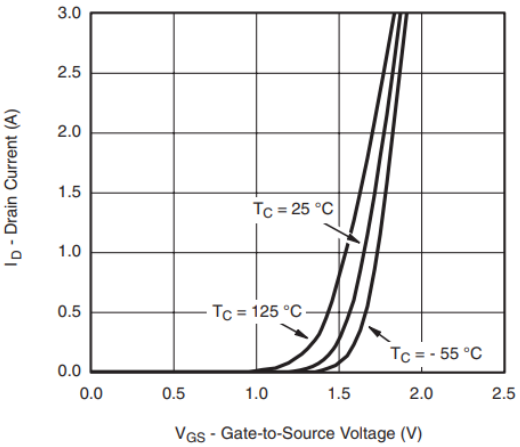
➢ **Electronics Characteristics**(T_A=25℃ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ.	Max	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	VGS=0V,ID=-250uA	-20			V
$V_{GS\ (th)}$	Gate Threshold Voltage	VDS=VGS,ID=-250uA	-0.5	-0.7	-1.2	V
$R_{DS(on)}$	Drain-Source On-Resistance	VGS=-4.5V,ID=-2.8A		63	80	mR
		VGS=-2.5V,ID=-2.3A		87	110	
		VGS=-1.8V,ID=-0.5A		120	160	
I_{DSS}	Zero Gate Voltage Drain Current	VDS=-20V,VGS=0V			-1	uA
I_{GSS}	Gate-Source leak current	VGS=±12V,VDS=0V			±100	nA
G_{FS}	Transconductance	VDS=-5V,ID=-2A		4.5		S
V_{SD}	Forward Voltage	VGS=0V,IS=-0.9A		-0.7	-1.2	V
Ciss	Input Capacitance	VDS=-10V, VGS=0V, f=1MHz		450		pF
Coss	Output Capacitance			180		
Crss	Reverse Transfer Capacitance			90		
Qg	Total Gate charge	VGS=-4.5V , VDS=-15V , ID=-3A		6		nC
Qgs	Gate to Source charge			1		
Qgd	Gate to Drain charge			1.5		
$T_{D(ON)}$	Turn-on delay time	VGS=-4.5V, VDS=-10V, RL=6R, RG=3R,ID=-1A		20		ns
Tr	Rise time			14		
$T_{D(OFF)}$	Turn-off delay time			44		
Tf	Fall time			16		

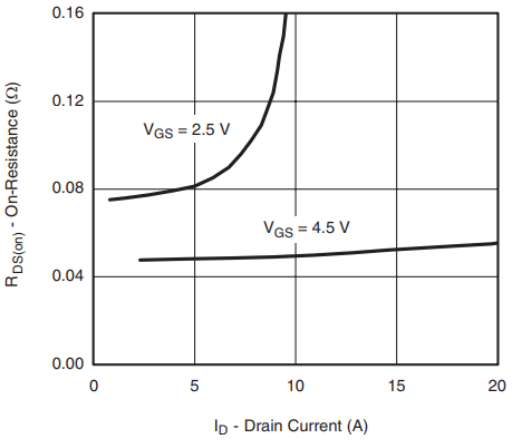
➢ Typical Characteristics(T_A=25℃ unless otherwise noted)



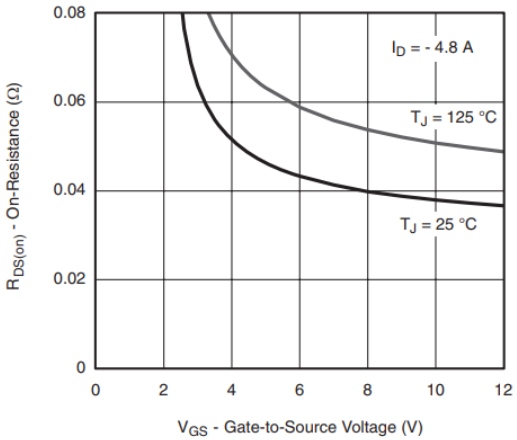
Output Characteristics



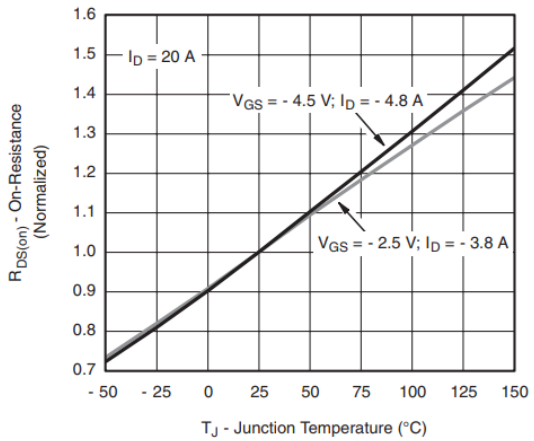
Transfer Characteristics



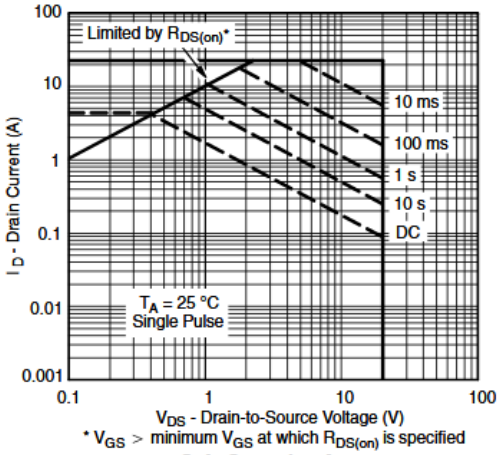
On-Resistance vs. Drain Current and Gate Voltage



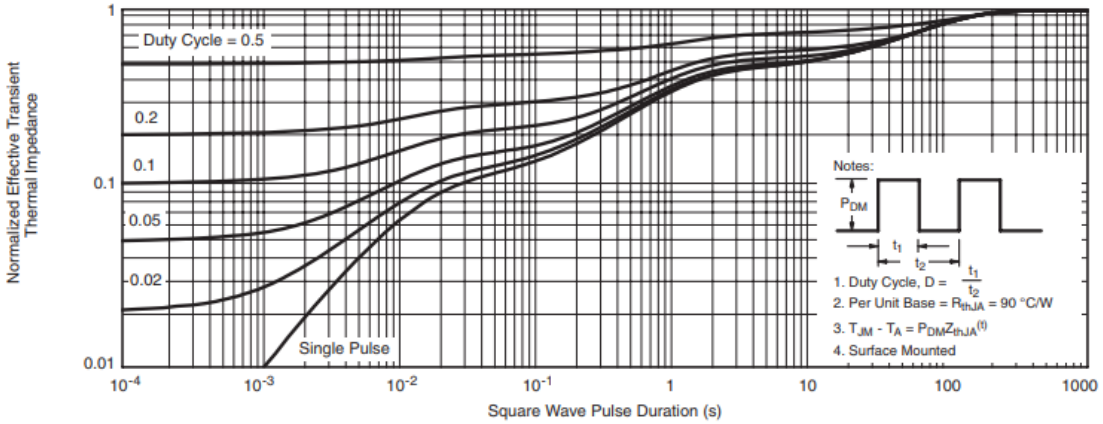
On-Resistance vs. Gate-to-Source Voltage



On-Resistance vs. Junction Temperature

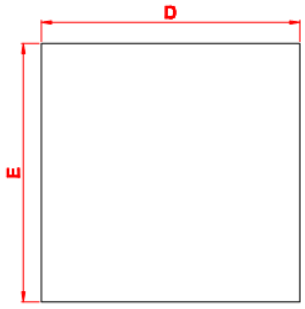


Safe Operating Area

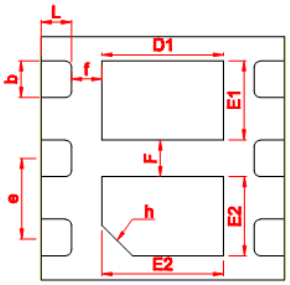


Normalized Thermal Transient Impedance, Junction-to-Ambient

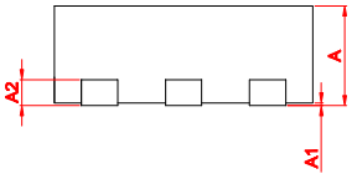
➢ Package Information



TOP VIEW



BOTTOM VIEW



SIDE VIEW

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.700	0.750	0.800
* A1	0.000	0.020	0.050
* b	0.275	0.300	0.325
* A2	0.190	0.210	0.230
* D	1.900	2.000	2.100
* E	1.900	2.000	2.100
* E1	0.570	0.620	0.670
* E2	0.570	0.620	0.670
* D1	0.950	1.000	1.050
* D2	0.950	1.000	1.050
* e	0.600	0.650	0.700
h	0.300	0.350	0.400
* L	0.200	0.250	0.300
* F	0.250	0.300	0.350
* f	0.200	0.250	0.300

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